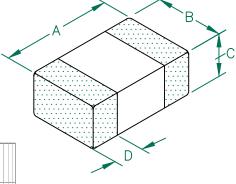
CPI0806KR82R-10

PHYSICAL DIMENSIONS:

± 0.15[.006] A 2.00 [.079]

± 0.15[.006] B 1.60 [.063] ± 0.10[.004] C 0.90 [.035]

± 0.20[.008] D 0.50 [.020]



	ELECTRICAL CHARACTERISTICS:									
	L (µH) @ 1MHz ± 20%	DCR ($\frac{\Omega}{2}$) ± 30%	l (Max)							
Non	0.820	0.1600								
Min	0.656	0.1120								
Max	0.984	0.2080	1500mA							

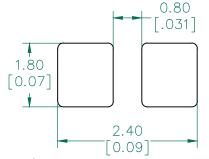
NOTES: UNLESS OTHERWISE SPECIFIED

- 1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 3000 PCS/REEL, EMBOSSED PLASTIC TAPE.
- 2. TERMINATION FINISH IS 100% MATTE Sn OVER Ni.
- 3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 4. I (MAX.) IS BASED ON THE MAXIMUM SUSTAINED CURRENT APPLIED WHILE MAINTAINING A MAXIMUM TEMPERATURE RISE OF 40°C OVER AMBIENT.
- 5. OPERATION TEMPERATURE TEMP: -55°C~+125°C (INCLUDING SELF-HEATING)

2.0 nductance(uH) 0.010 100 1,000 Frequency (MHz)

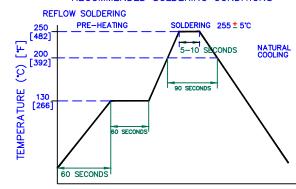
Ls vs Frequency

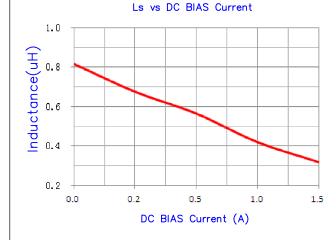
LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.763 [0.030] to this dimension)

RECOMMENDED SOLDERING CONDITIONS







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